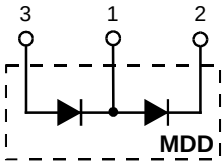
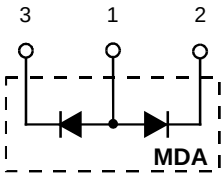
Diode Modules

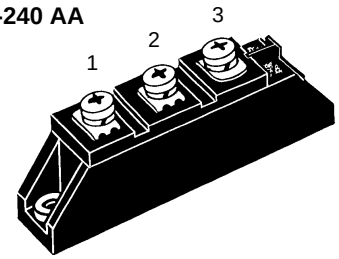
I_{FRMS} = 2x 180 A
I_{FAVM} = 2x 113 A
V_{RRM} = 800-1800 V

V_{RSM} V	V_{RRM} V	Type	
900	800	MDD 72-08N1 B	MDA 72-08N1 B
1300	1200	MDD 72-12N1 B	---
1500	1400	MDD 72-14N1 B	MDA 72-14N1 B
1700	1600	MDD 72-16N1 B	MDA 72-16N1 B
1900	1800	MDD 72-18N1 B	---





TO-240 AA



Symbol	Test Conditions		Maximum Ratings	
I_{FRMS}	$T_{VJ} = T_{VJM}$		180	A
I_{FAVM}	T_C = 92°C; 180° sine		113	A
	T_C = 100°C; 180° sine		99	A
I_{FSM}	T_{VJ} = 45°C;	t = 10 ms (50 Hz), sine	1700	A
	V_R = 0	t = 8.3 ms (60 Hz), sine	1950	A
	$T_{VJ} = T_{VJM}$	t = 10 ms (50 Hz), sine	1540	A
	V_R = 0	t = 8.3 ms (60 Hz), sine	1800	A
$\int i^2dt$	T_{VJ} = 45°C	t = 10 ms (50 Hz), sine	14 450	A^2s
	V_R = 0	t = 8.3 ms (60 Hz), sine	15 700	A^2s
	$T_{VJ} = T_{VJM}$	t = 10 ms (50 Hz), sine	11 850	A^2s
	V_R = 0	t = 8.3 ms (60 Hz), sine	13 400	A^2s
T_{VJ}			-40...+150	°C
T_{VJM}			150	°C
T_{stg}			-40...+125	°C
V_{ISOL}	50/60 Hz, RMS	t = 1 min	3000	V~
	$I_{ISOL} \leq$ 1 mA	t = 1 s	3600	V~
M_d	Mounting torque (M5)		2.5-4/22-35	Nm/lb.in.
	Terminal connection torque (M5)		2.5-4/22-35	Nm/lb.in.
Weight	Typical including screws		90	g

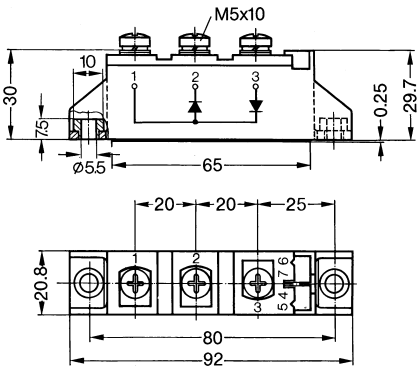
Symbol	Test Conditions		Characteristic Values	
I_R	$T_{VJ} = T_{VJM}$; $V_R = V_{RRM}$		15	mA
V_F	I_F = 300 A; T_{VJ} = 25°C		1.6	V
V_{T0}	For power-loss calculations only		0.8	V
r_T	$T_{VJ} = T_{VJM}$		2.3	mΩ
Q_S	T_{VJ} = 125°C; I_F = 50 A, -di/dt = 3 A/µs		170	µC
I_{RM}			45	A
R_{thJC}	per diode; DC current	other values see Fig. 6/7	0.35	K/W
	per module		0.175	K/W
R_{thJK}	per diode; DC current		0.55	K/W
	per module		0.275	K/W
d_S	Creepage distance on surface		12.7	mm
d_A	Strike distance through air		9.6	mm
a	Maximum allowable acceleration		50	m/s^2

Features
- International standard package JEDEC TO-240 AA
- Direct copper bonded Al_2O_3 -ceramic base plate
- Planar passivated chips
- Isolation voltage 3600 V~
- UL registered, E 72873

Applications
- Supplies for DC power equipment
- DC supply for PWM inverter
- Field supply for DC motors
- Battery DC power supplies

Advantages
- Space and weight savings
- Simple mounting
- Improved temperature and power cycling
- Reduced protection circuits

Dimensions in mm (1 mm = 0.0394")



Data according to IEC 60747 and refer to a single diode unless otherwise stated.
IXYS reserves the right to change limits, test conditions and dimensions

025

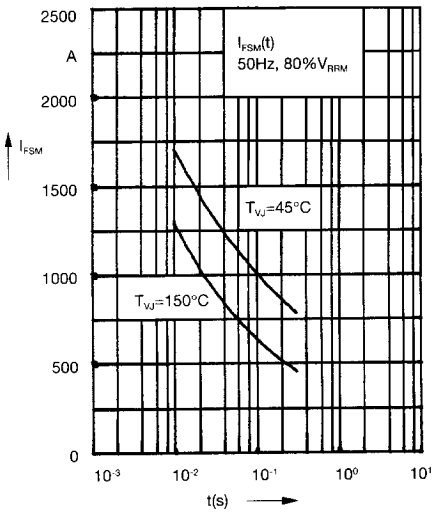


Fig. 1 Surge overload current
I_{FSM}: Crest value, t: duration

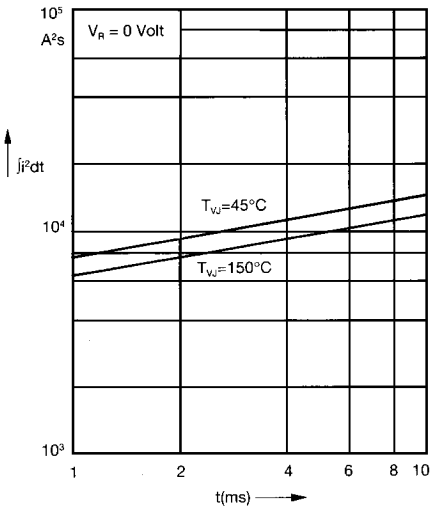


Fig. 2 $\int i^2dt$ versus time (1-10 ms)

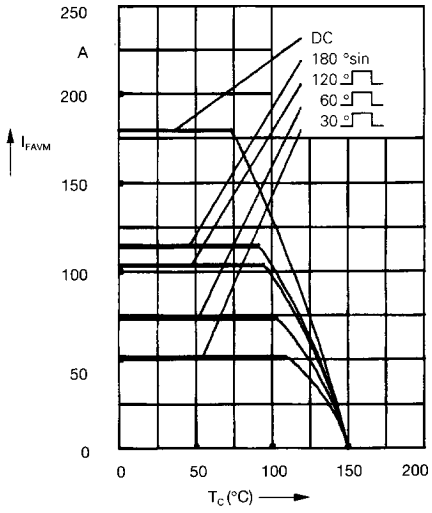


Fig. 2a Maximum forward current at case temperature

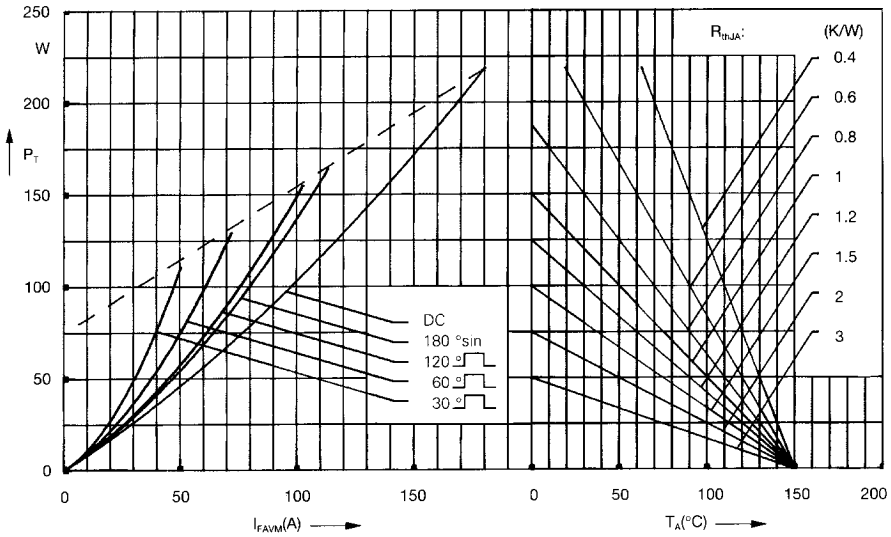


Fig. 3 Power dissipation versus forward current and ambient temperature (per diode)

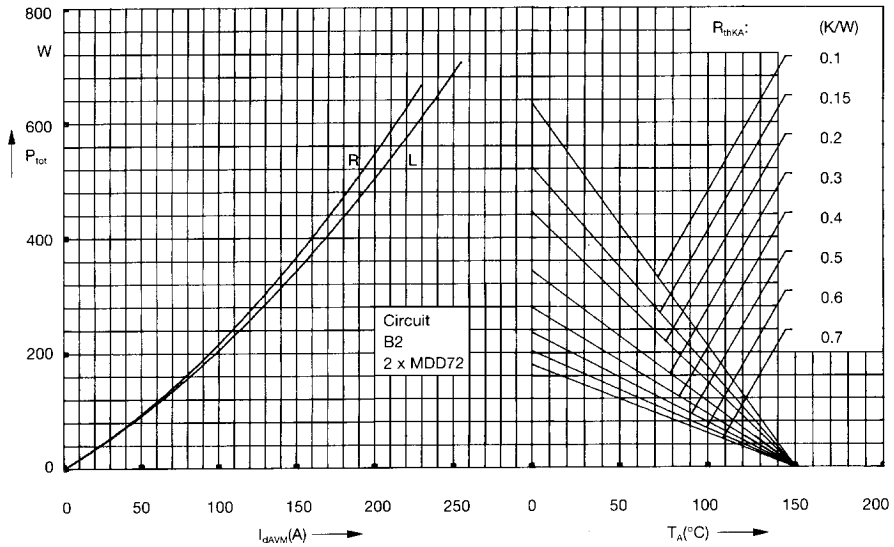


Fig. 4 Single phase rectifier bridge: Power dissipation versus direct output current and ambient temperature
R = resistive load
L = inductive load

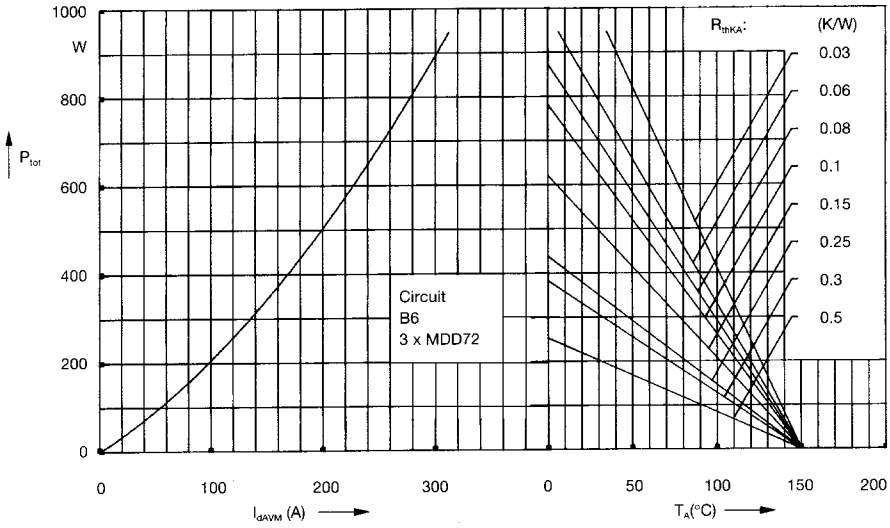


Fig. 5 Three phase rectifier bridge: Power dissipation versus direct output current and ambient temperature

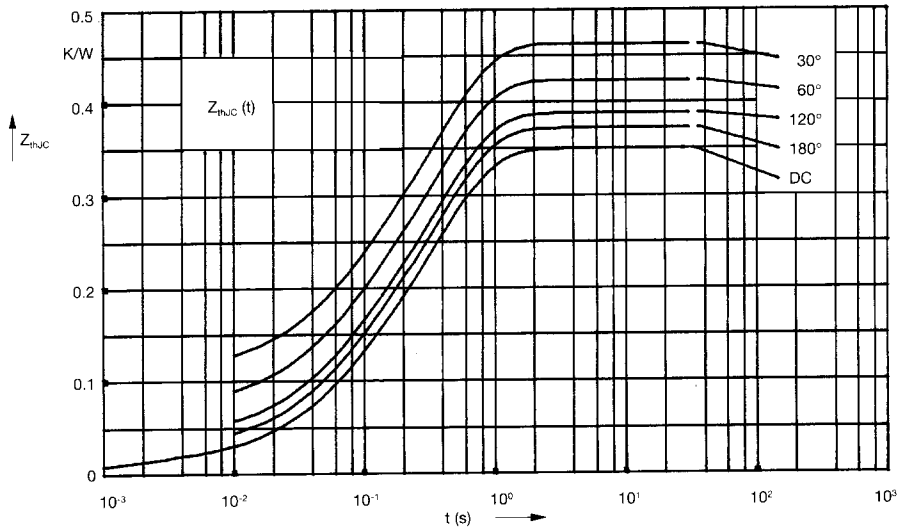


Fig. 6 Transient thermal impedance junction to case (per diode)

R_{thJC} for various conduction angles d:

d	R_{thJC} (K/W)
DC	0.35
180°	0.37
120°	0.39
60°	0.43
30°	0.47

Constants for Z_{thJC} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.013	0.0014
2	0.072	0.062
3	0.265	0.375

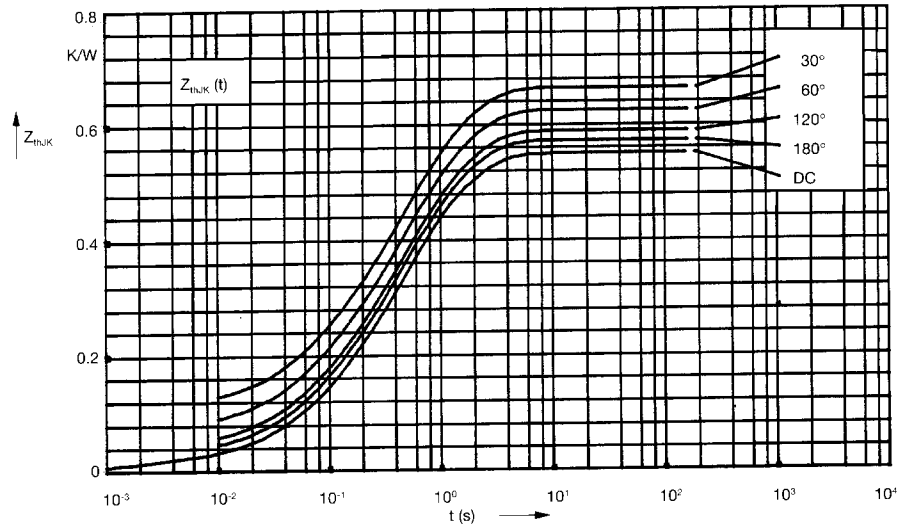


Fig. 7 Transient thermal impedance junction to heatsink (per diode)

R_{thJK} for various conduction angles d:

d	R_{thJK} (K/W)
DC	0.55
180°	0.57
120°	0.59
60°	0.63
30°	0.67

Constants for Z_{thJK} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.013	0.0014
2	0.072	0.062
3	0.265	0.375
4	0.2	1.32